

TOSHIBA Field Effect Transistor Silicon P/N Channel MOS Type

# SSM6L10TU

## High Speed Switching Applications

- Optimum for high-density mounting in small packages
- Low on-resistance    Q1:  $R_{on} = 395\text{m}\Omega$  (max) (@ $V_{GS} = 1.8\text{ V}$ )  
                               Q2:  $R_{on} = 980\text{m}\Omega$  (max) (@ $V_{GS} = -1.8\text{ V}$ )

### Q1 Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Characteristics	Symbol	Rating	Unit
Drain-Source voltage	$V_{DS}$	20	V
Gate-Source voltage	$V_{GSS}$	$\pm 12$	V
Drain current	DC	$I_D$	A
	Pulse	$I_{DP}$	
		0.5	
		1.5	

### Q2 Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

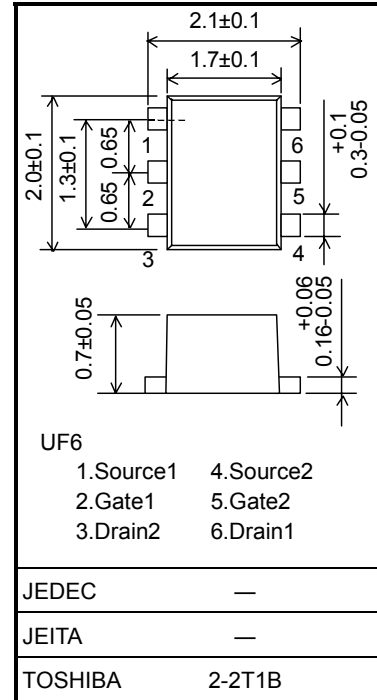
Characteristics	Symbol	Rating	Unit
Drain-Source voltage	$V_{DS}$	-20	V
Gate-Source voltage	$V_{GSS}$	$\pm 8$	V
Drain current	DC	$I_D$	A
	Pulse	$I_{DP}$	
		-0.5	
		-1.5	

### Maximum Ratings (Q1,Q2 Common)( $T_a = 25^\circ\text{C}$ )

Characteristics	Symbol	Rating	Unit
Drain power dissipation	$P_D$ (Note1)	500	mW
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature range	$T_{stg}$	-55~150	$^\circ\text{C}$

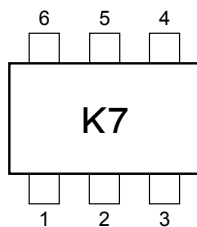
Note1: Mounted on FR4 board. (total dissipation)  
 (25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu Pad: 645 mm<sup>2</sup>)

Unit: mm

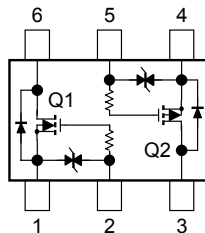


Weight: 7.0 mg (typ.)

### Marking



### Equivalent Circuit (top view)



### Handling Precaution

When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

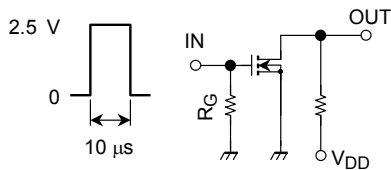
## Q1 Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 12V, V_{DS} = 0$	—	—	$\pm 1$	$\mu A$
Drain-Source breakdown voltage	$V_{(BR) DSS}$	$I_D = 1 mA, V_{GS} = 0$	20	—	—	V
	$V_{(BR) DSX}$	$I_D = 1 mA, V_{GS} = -12 V$	10	—	—	
Drain cut-off current	$I_{DSS}$	$V_{DS} = 20 V, V_{GS} = 0$	—	—	1	$\mu A$
Gate threshold voltage	$V_{th}$	$V_{DS} = 3 V, I_D = 0.1 mA$	0.5	—	1.1	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 3 V, I_D = 0.25 A$ (Note2)	1.2	2.4	—	S
Drain-Source on-resistance	$R_{DS(ON)}$	$I_D = 0.25 A, V_{GS} = 4.0 V$ (Note2)	—	125	145	$m\Omega$
		$I_D = 0.25 A, V_{GS} = 2.5 V$ (Note2)	—	150	190	
		$I_D = 0.25 A, V_{GS} = 1.8 V$ (Note2)	—	200	395	
Input capacitance	$C_{iss}$	$V_{DS} = 10 V, V_{GS} = 0, f = 1 MHz$	—	268	—	pF
Reverse transfer capacitance	$C_{rss}$	$V_{DS} = 10 V, V_{GS} = 0, f = 1 MHz$	—	34	—	pF
Output capacitance	$C_{oss}$	$V_{DS} = 10 V, V_{GS} = 0, f = 1 MHz$	—	44	—	pF
Switching time	Turn-on time	$t_{on}$	—	11	—	ns
	Turn-off time	$t_{off}$	—	15	—	

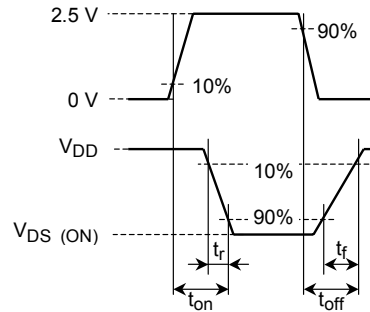
Note2: Pulse test

## Switching Time Test Circuit

## (a) Test Circuit



$V_{DD} = 10 V$   
 $R_G = 4.7 \Omega$   
 $D.U. \leq 1\%$   
 $V_{IN}$ :  $t_r, t_f < 5 ns$   
 Common Source  
 $T_a = 25^\circ C$

(b)  $V_{IN}$ (c)  $V_{OUT}$ 

## Precaution

$V_{th}$  can be expressed as the voltage between gate and source when the low operating current value is  $I_D = 100 \mu A$  for this product. For normal switching operation,  $V_{GS(on)}$  requires a higher voltage than  $V_{th}$  and  $V_{GS(off)}$  requires a lower voltage than  $V_{th}$ .

(The relationship can be established as follows:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ )

Please take this into consideration when using the device. The  $V_{GS}$  recommended voltage for turning on this product is 1.8 V or higher.

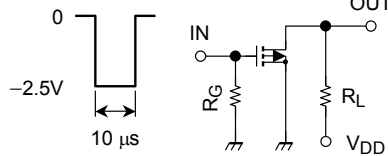
## Q2 Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0$	—	—	$\pm 1$	$\mu\text{A}$
Drain-Source breakdown voltage	$V_{(BR)DSS}$	$I_D = -1 \text{ mA}, V_{GS} = 0$	-20	—	—	V
	$V_{(BR)DSX}$	$I_D = -1 \text{ mA}, V_{GS} = +8 \text{ V}$	-12	—	—	
Drain cut-off current	$I_{DSS}$	$V_{DS} = -20 \text{ V}, V_{GS} = 0$	—	—	-1	$\mu\text{A}$
Gate threshold voltage	$V_{th}$	$V_{DS} = -3 \text{ V}, I_D = -0.1 \text{ mA}$	-0.5	—	-1.1	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = -3 \text{ V}, I_D = -0.25 \text{ A}$ (Note3)	0.8	1.7	—	S
Drain-Source on-resistance	$R_{DS(ON)}$	$I_D = -0.25 \text{ A}, V_{GS} = -4 \text{ V}$ (Note3)	—	200	230	$\text{m}\Omega$
		$I_D = -0.25 \text{ A}, V_{GS} = -2.5 \text{ V}$ (Note3)	—	260	330	
		$I_D = -0.25 \text{ A}, V_{GS} = -1.8 \text{ V}$ (Note3)	—	400	980	
Input capacitance	$C_{iss}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	250	—	pF
Reverse transfer capacitance	$C_{rss}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	35	—	pF
Output capacitance	$C_{oss}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	45	—	pF
Switching time	Turn-on time	$V_{DD} = -10 \text{ V}, I_D = -0.25 \text{ A},$ $V_{GS} = 0 \sim -2.5 \text{ V}, R_G = 4.7 \Omega$	—	14	—	ns
	Turn-off time		—	15	—	

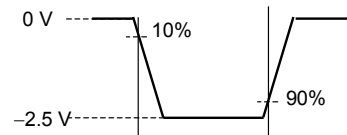
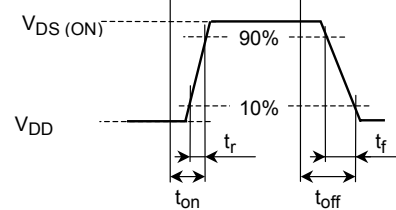
Note3: Pulse test

## Switching Time Test Circuit

(a) Test circuit



$V_{DD} = -10 \text{ V}$   
 $R_G = 4.7 \Omega$   
 $\text{D.U.} \leq 1\%$   
 $V_{IN}: t_r, t_f < 5 \text{ ns}$   
 Common Source  
 $T_a = 25^\circ\text{C}$

(b)  $V_{IN}$ (c)  $V_{OUT}$ 

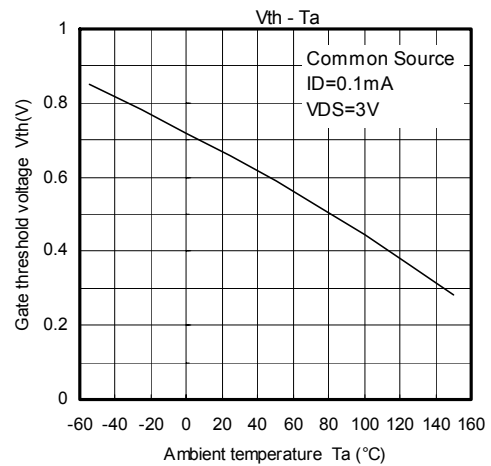
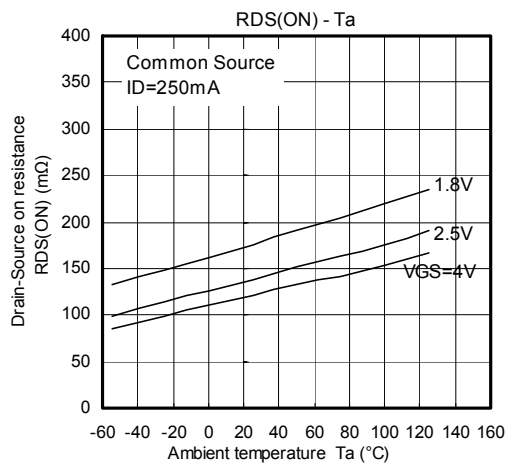
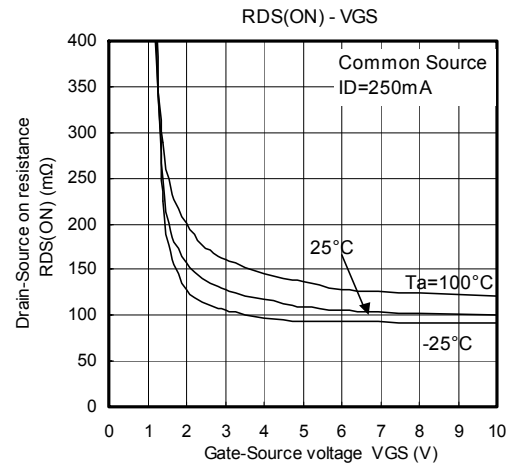
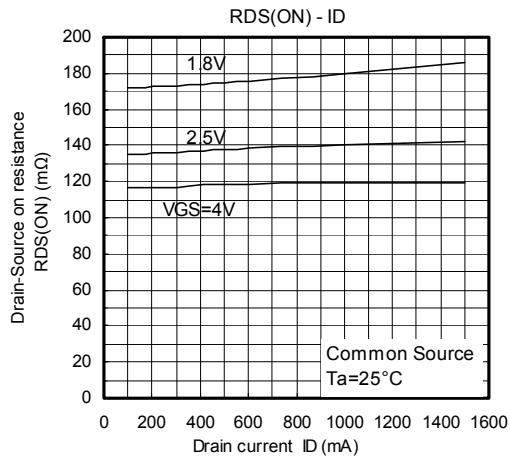
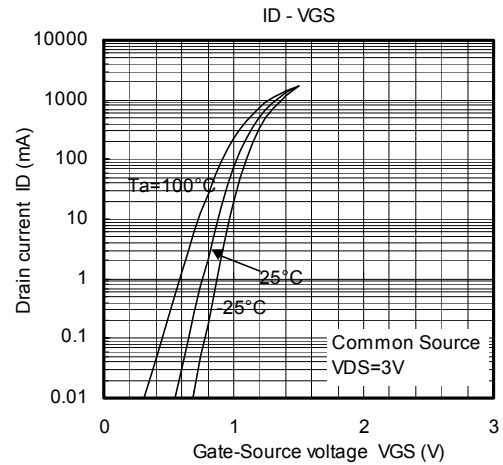
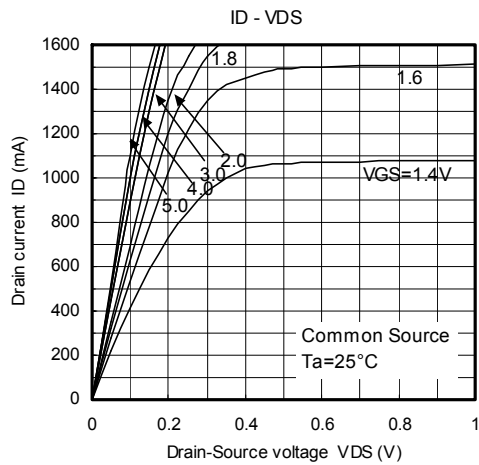
## Precaution

$V_{th}$  can be expressed as the voltage between gate and source when the low operating current value is  $I_D = -100 \mu\text{A}$  for this product. For normal switching operation,  $V_{GS(on)}$  requires a higher voltage than  $V_{th}$  and  $V_{GS(off)}$  requires a lower voltage than  $V_{th}$ .

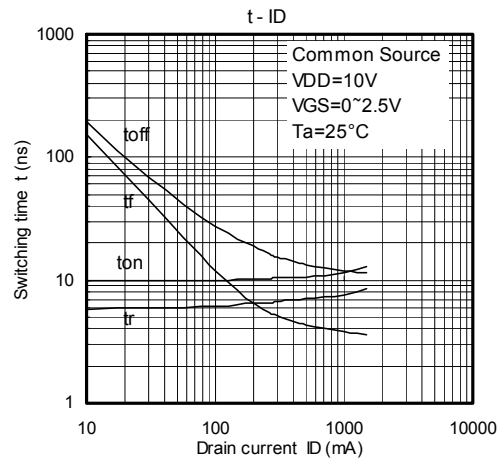
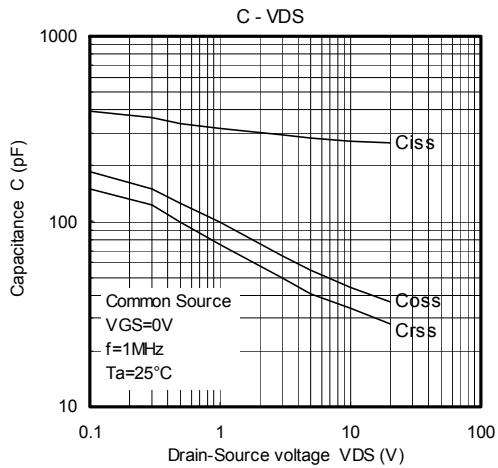
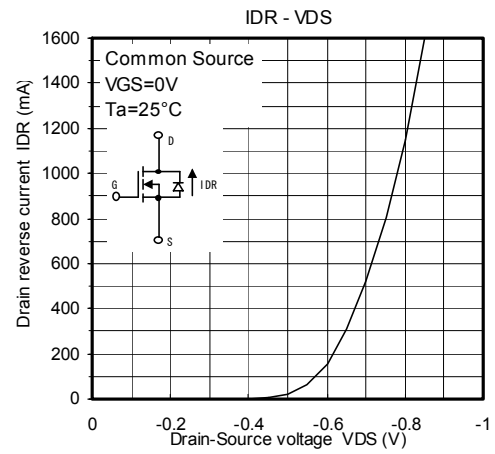
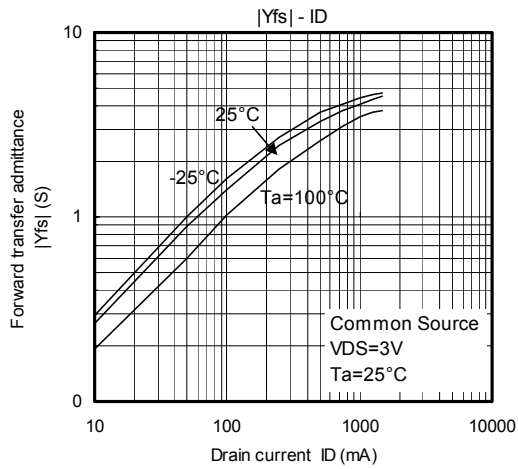
(The relationship can be established as follows:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ )

Please take this into consideration when using the device. The  $V_{GS}$  recommended voltage for turning on this product is -1.8 V or higher.

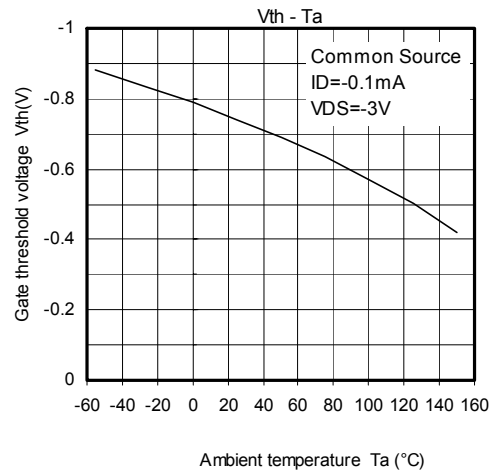
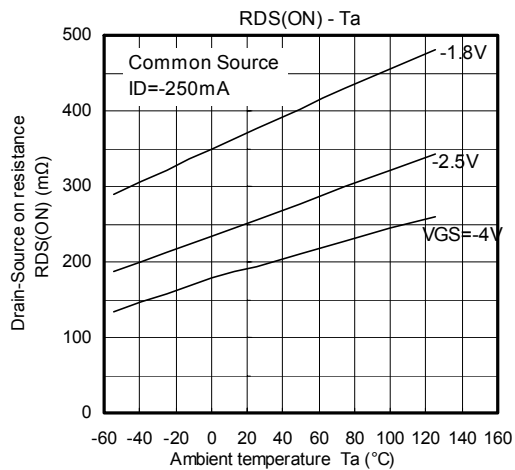
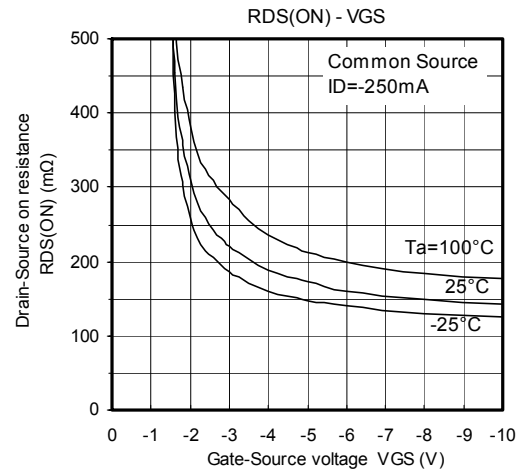
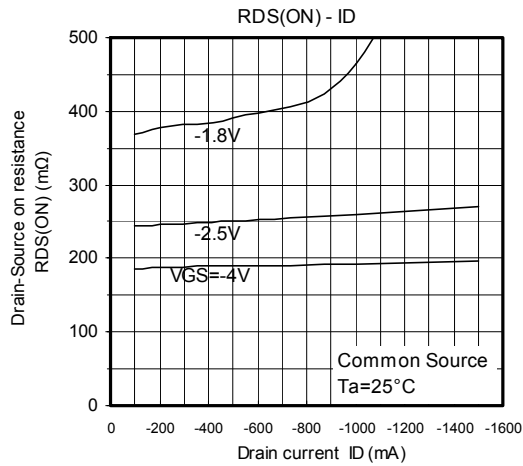
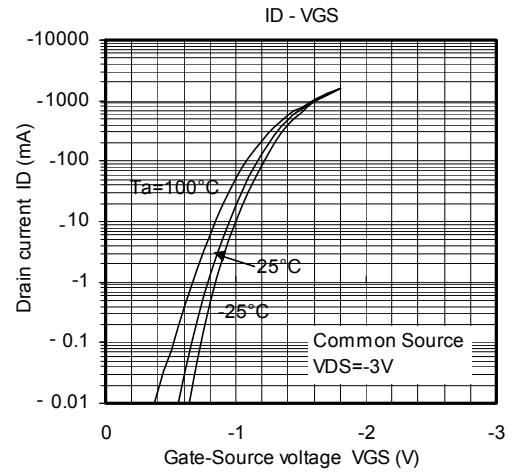
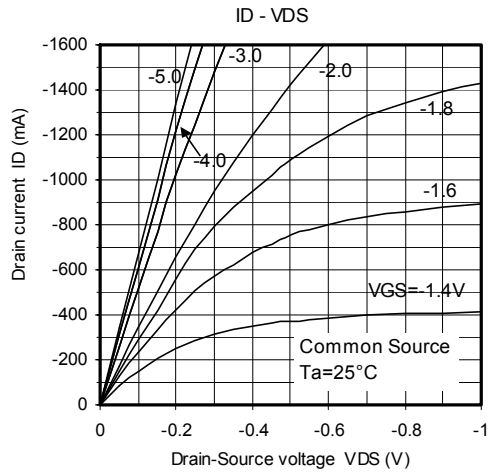
## Q1(Nch MOS FET)



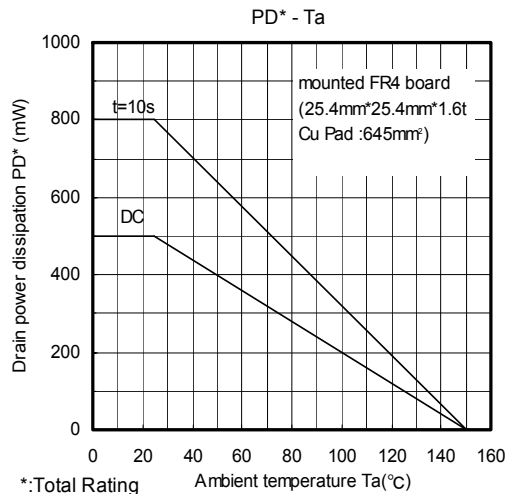
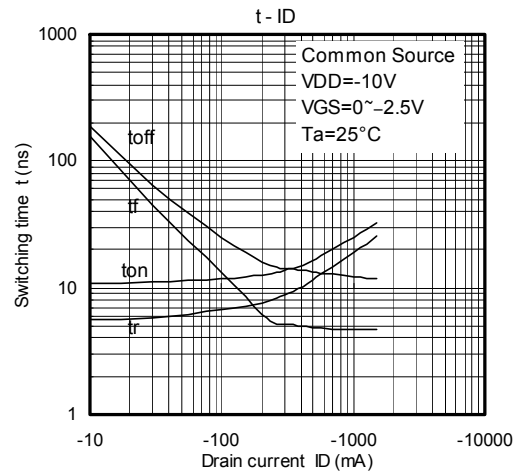
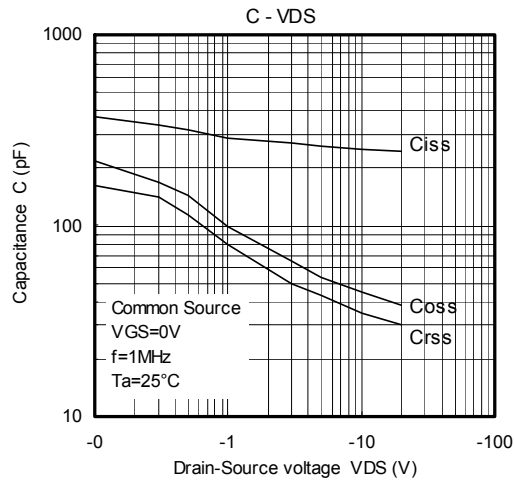
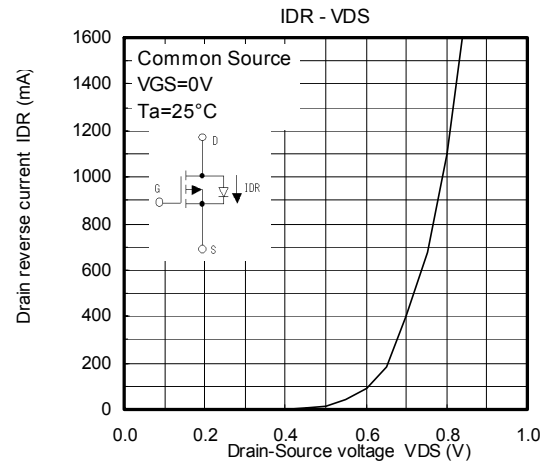
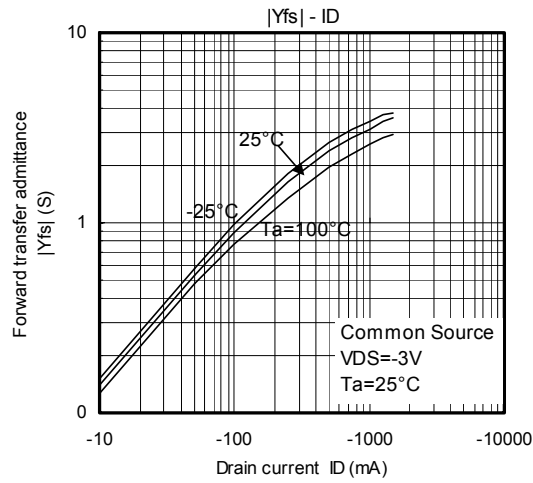
**Q1(Nch MOS FET)**

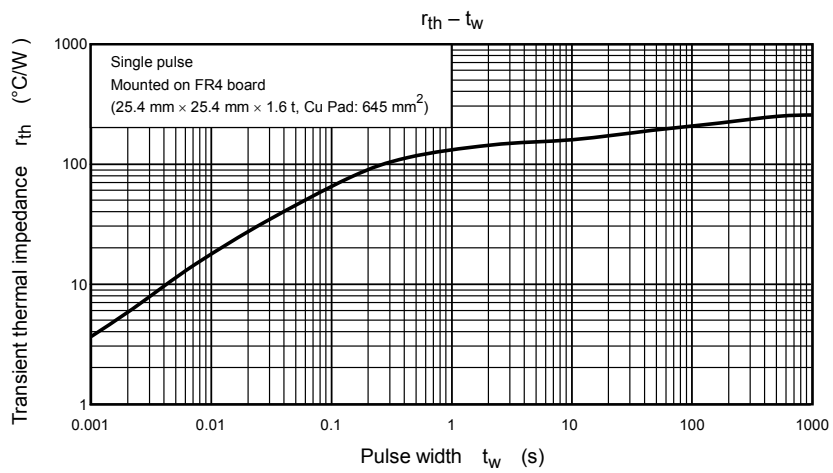


## Q2(Pch MOS FET)



## Q2(Pch MOS FET)







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